



Description

The HXY10N65F can be used in various power switching circuit for system miniaturization and higher efficiency. The package form is TO-220F, which accords with the RoHS standard.



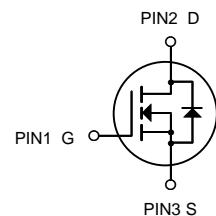
TO-220F

General Features

$V_{DS} = 650V$, $I_D = 10A$
 $R_{DS(ON)} < 1.05\Omega$ @ $V_{GS}=10V$

Application

- Power switch circuit of adaptor and charger.



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Units Tube
HXY10N65F	TO-220F	10N65 XXX YYYY	50

Absolute Maximum Ratings@ $T_j=25^\circ C$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	650	V
V_{GS}	Gate-Source Voltage	± 30	V
$I_D @ T_c=25^\circ C$	Drain Current, $V_{GS} @ 4.5V$	10	A
$I_D @ T_c=100^\circ C$	Drain Current, $V_{GS} @ 4.5V$	6.3	A
IDM	Pulsed Drain Current ¹	40	A
$P_D @ T_c=25^\circ C$	Total Power Dissipation	40	W
E_{AS}	Single Pulse Avalanche Energy ⁴	500	mJ
TSTG	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C



Electrical Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified):

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Unit
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu\text{A}$	650	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Bvdss Temperature Coefficient	$I_D=250\mu\text{A}, \text{Reference } 25^\circ\text{C}$	--	0.7	--	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain to Source Leakage Current	$V_{DS}=650\text{V}, V_{GS}=0\text{V}, T_a = 25^\circ\text{C}$	--	--	1	μA
		$V_{DS}=520\text{V}, V_{GS}=0\text{V}, T_a = 125^\circ\text{C}$	--	--	100	μA
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS}=+30\text{V}$	--	--	100	nA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS}=-30\text{V}$	--	--	-100	nA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=10\text{V}, I_D=5\text{A}$	--	0.86	1.05	Ω
$V_{GS(\text{TH})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	--	4.0	V
Pulse width $t_p \leqslant 300\mu\text{s}, \delta \leqslant 2\%$						

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g_{fs}	Forward Transconductance	$V_{DS}=15\text{V}, I_D=5\text{A}$	--	9.5	--	S
C_{iss}	Input Capacitance		--	1642	--	pF
C_{oss}	Output Capacitance	$V_{GS} = 0\text{V} V_{DS} = 25\text{V}$ $f = 1.0\text{MHz}$	--	128	--	
C_{rss}	Reverse Transfer Capacitance		--	7	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D = 10\text{A} V_{DD} = 325\text{V}$ $R_G = 10\Omega$	--	27	--	ns
t_r	Rise Time		--	22	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	53	--	
t_f	Fall Time		--	24	--	
Q_g	Total Gate Charge	$I_D = 10\text{A} V_{DD} = 520\text{V}$ $V_{GS} = 10\text{V}$	--	32	--	nC
Q_{gs}	Gate to Source Charge		--	8	--	
Q_{gd}	Gate to Drain ("Miller") Charge		--	12	--	



Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I _S	Continuous Source Current (Body Diode)		--	--	10	A
I _{SM}	Maximum Pulsed Current (Body Diode)		--	--	40	A
V _{SD}	Diode Forward Voltage	I _S =10A, V _{GS} =0V	--	--	1.5	V
trr	Reverse Recovery Time	I _S =10A, T _j = 25°C dI _F /dt=100A/us, V _{GS} =0V	--	528	--	ns
Qrr	Reverse Recovery Charge		--	3220	--	nC
I _{RRM}	Reverse Recovery Current		--	12.2	--	A

Pulse width tp ≤ 300μs, δ ≤ 2%

Symbol	Parameter	Typ.	Units
R _{θJC}	Junction-to-Case	3.13	°C/W
R _{θJA}	Junction-to-Ambient	62.5	°C/W

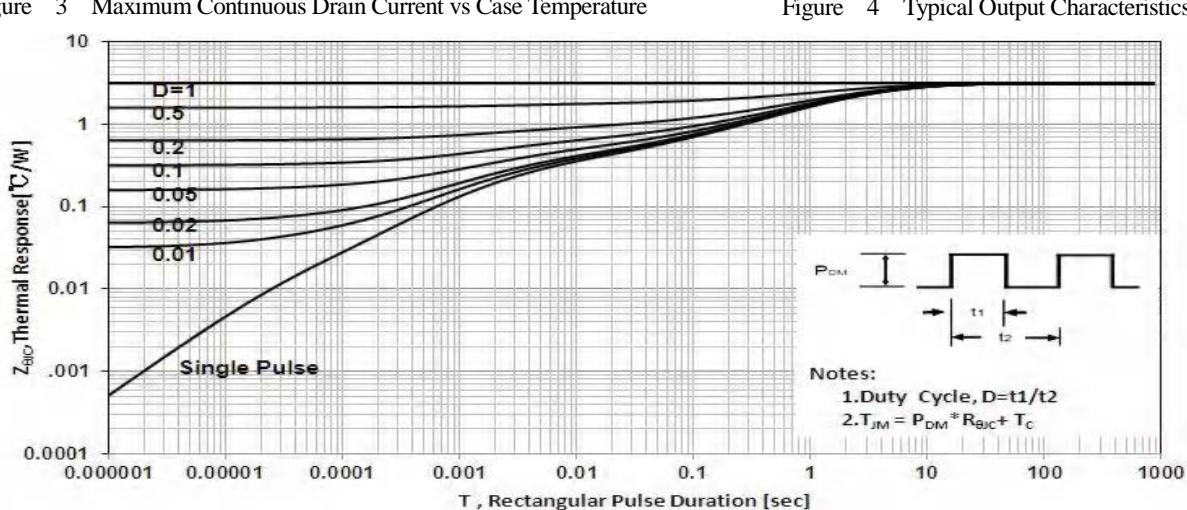
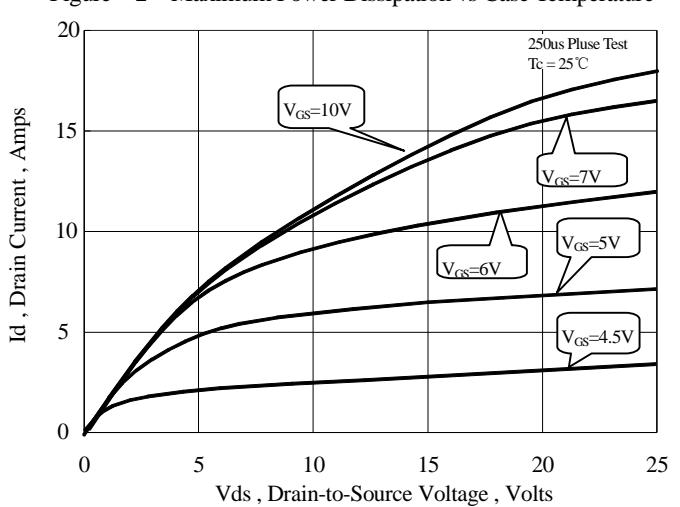
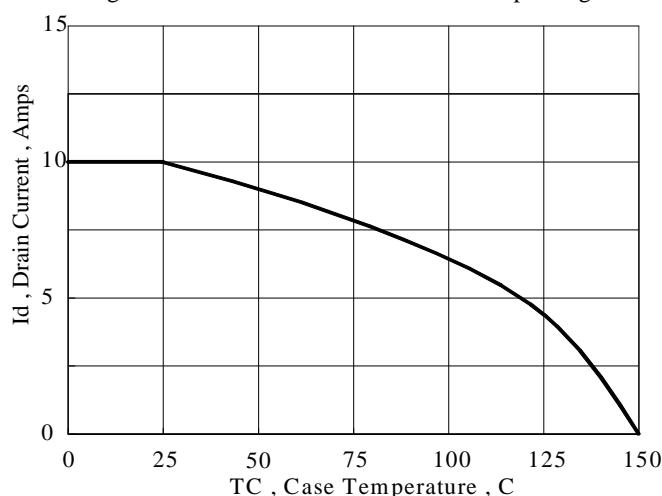
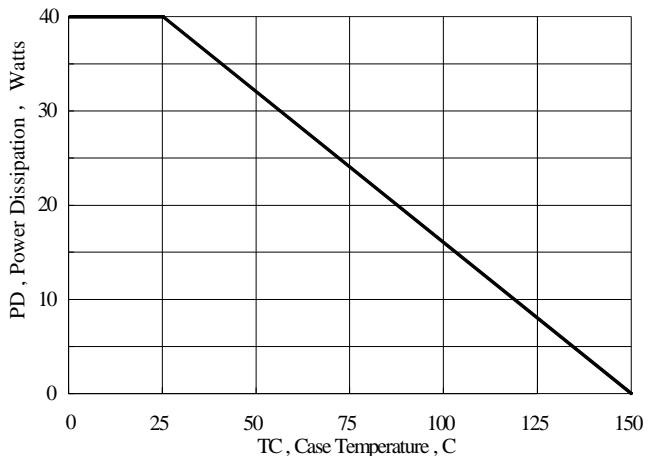
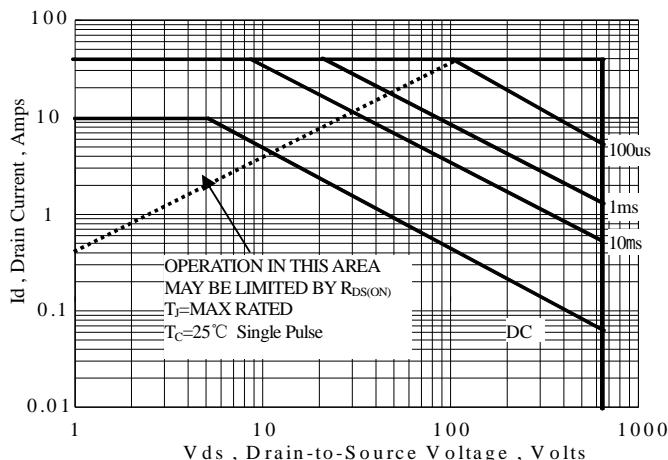
^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

^{a2}: L=10mH, I_D=10A, Start T_j=25°C

^{a3}: I_{SD}=10A, di/dt ≤ 100A/us, V_{DD} ≤ BV_{DS}, Start T_j=25°C



Characteristics Curve:



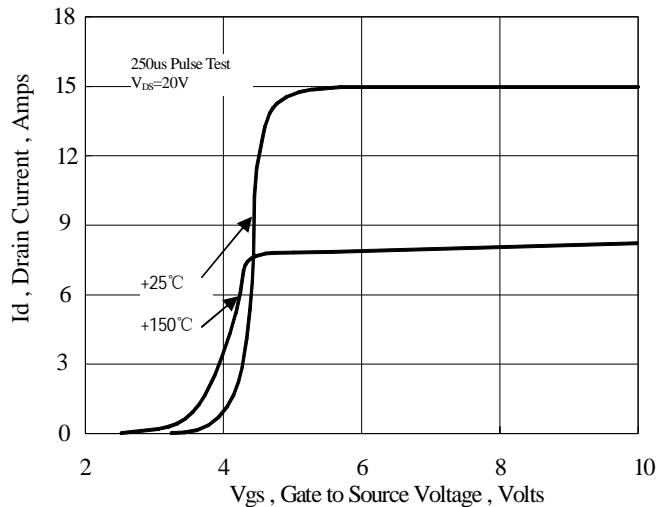


Figure 6 Typical Transfer Characteristics

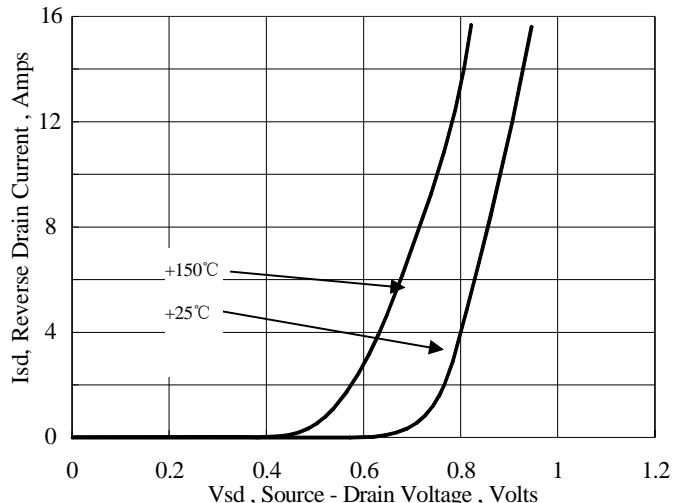


Figure 7 Typical Body Diode Transfer Characteristics

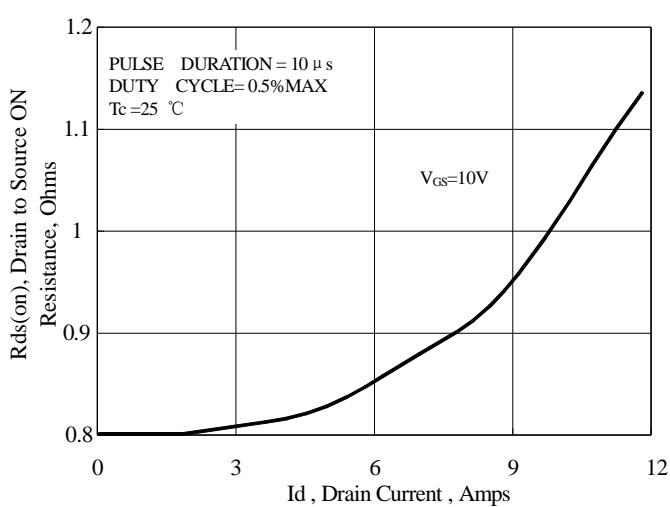


Figure 8 Typical Drain to Source ON Resistance
vs Drain Current

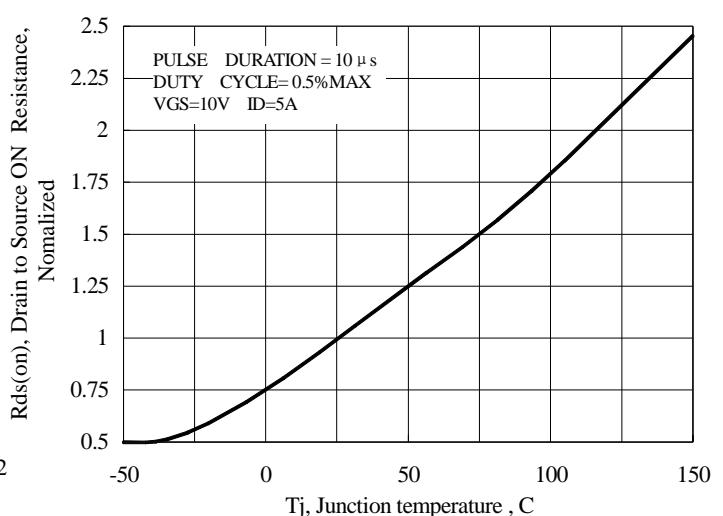
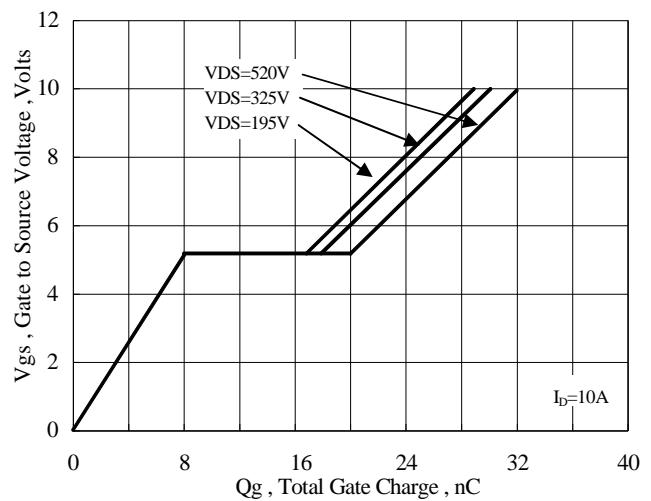
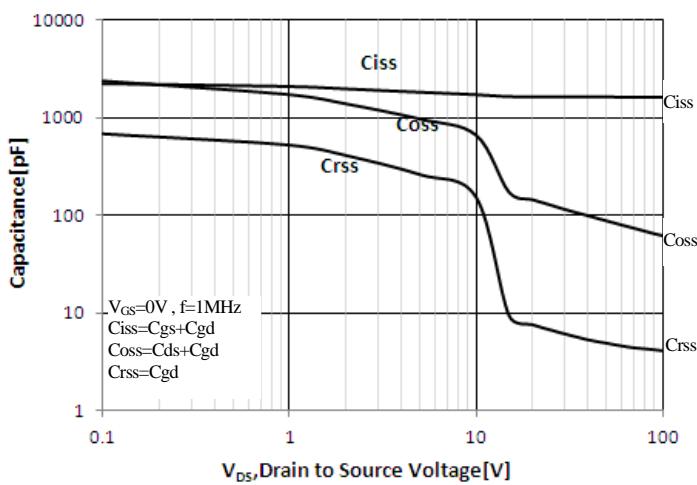
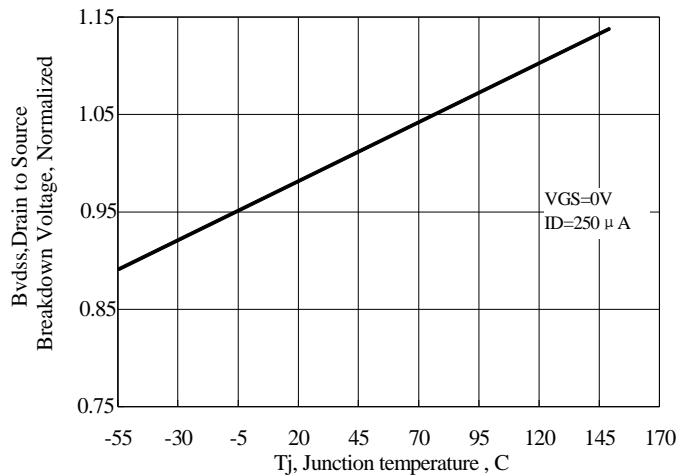
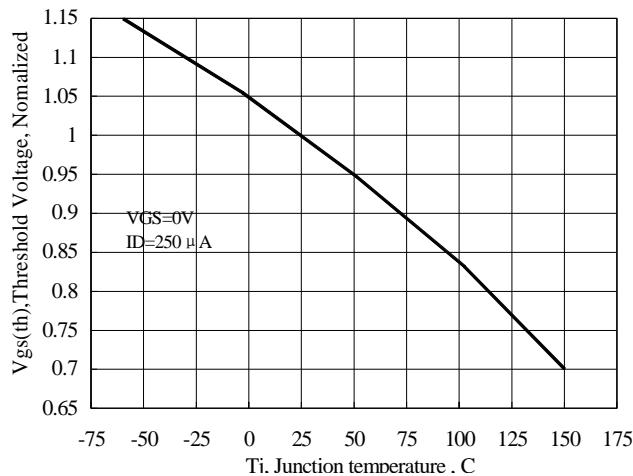


Figure 9 Typical Drain to Source on Resistance
vs Junction Temperature





Test Circuit and Waveform

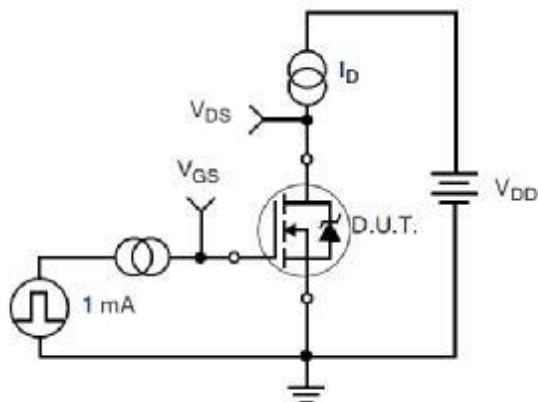


Figure 17. Gate Charge Test Circuit

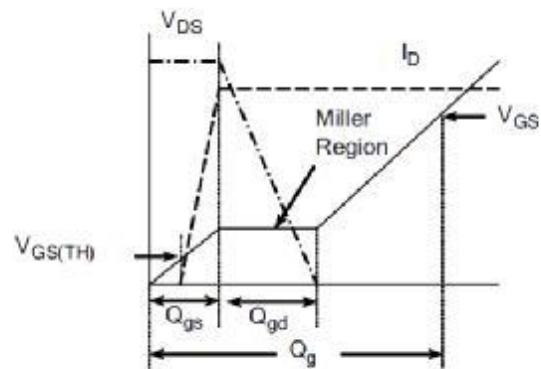


Figure 18. Gate Charge Waveform

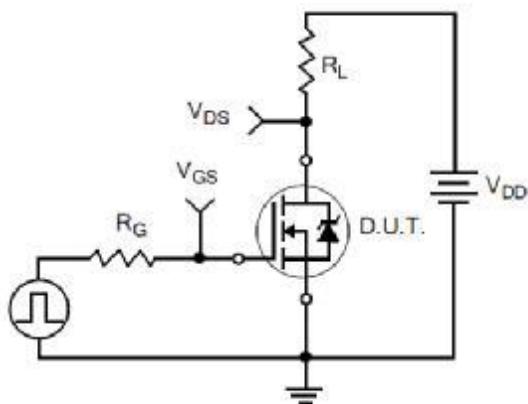


Figure 19. Resistive Switching Test Circuit

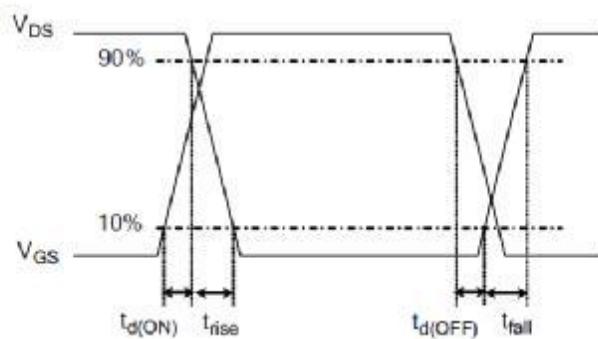


Figure 20. Resistive Switching Waveforms

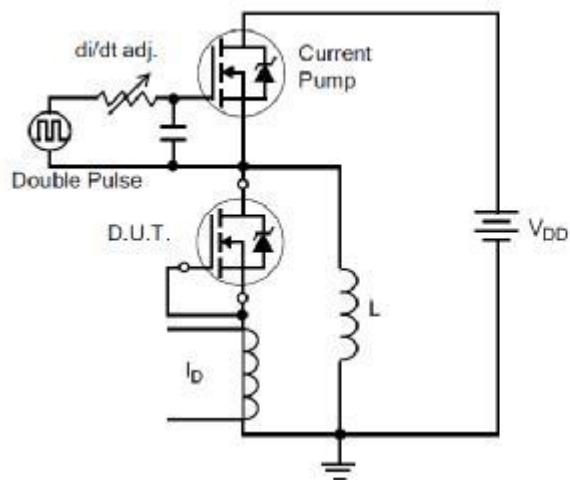


Figure 21. Diode Reverse Recovery Test Circuit

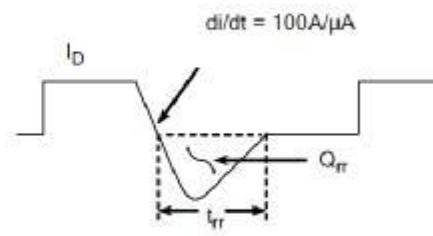


Figure 22. Diode Reverse Recovery Waveform

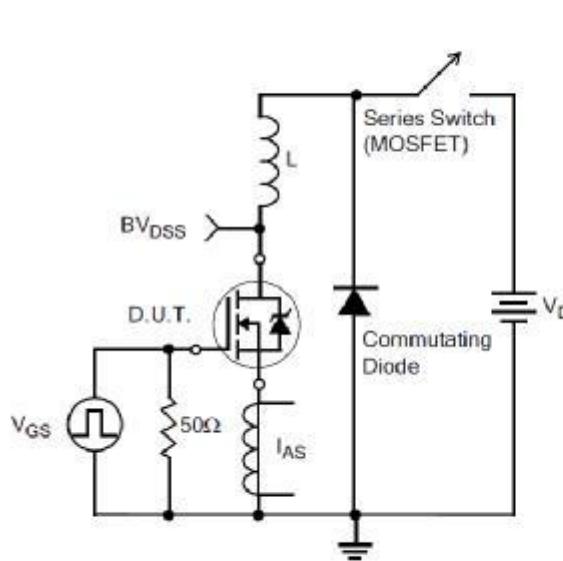


Figure 23. Unclamped Inductive Switching Test Circuit

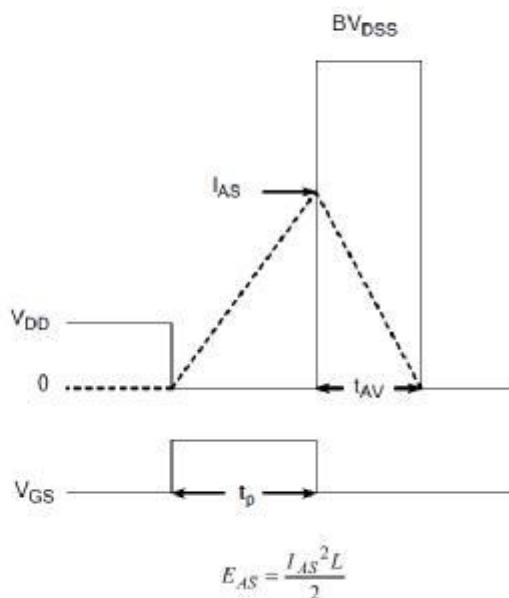
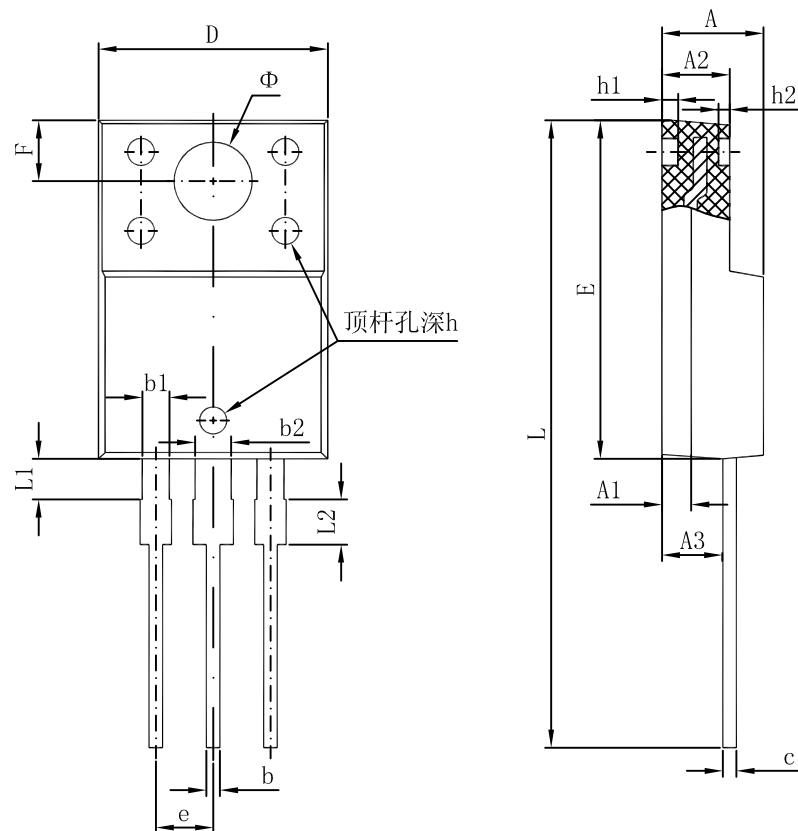


Figure 24. Unclamped Inductive Switching Waveforms



Package Information

TO-220F



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.300	4.700	0.169	0.185
A1	1.300	REF.	0.051	REF.
A2	2.800	3.200	0.110	0.126
A3	2.500	2.900	0.098	0.114
b	0.500	0.750	0.020	0.030
b1	1.100	1.350	0.043	0.053
b2	1.500	1.750	0.059	0.069
c	0.500	0.750	0.020	0.030
D	9.960	10.360	0.392	0.408
E	14.800	15.200	0.583	0.598
e	2.540	TYP.	0.100	TYP.
F	2.700	REF.	0.106	REF.
Φ	3.500	REF.	0.138	REF.
h	0.000	0.300	0.000	0.012
h1	0.800	REF.	0.031	REF.
h2	0.500	REF.	0.020	REF.
L	28.000	28.400	1.102	1.118
L1	1.700	1.900	0.067	0.075
L2	1.900	2.100	0.075	0.083



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